



TDA19978A

Quad HDMI 1.3a receiver interface with equalizer (HDTV up to 1080p, up to UXGA for PC's format)

Rev. 03 — 11 May 2010

Product data sheet

HDMI

1. General description

The TDA19978A is a four inputs HDMI 1.3a compliant receiver with embedded EDID memory.

The TDA19978A embeds an auto adaptive equalizer to improve the signal quality and to allow the use of a large range of cables (up to 25 m, laboratory tested, contact NXP Semiconductors for more details).

The HDCP keys set is stored in a non-volatile embedded memory for maximal security. Software drivers are delivered with the IC to ease configuration and use.

The TDA19978A supports:

- TV resolutions from 480i (1440 × 480i at 60 Hz) and 576i (1440 × 576i at 50 Hz) to HDTV (up to 1920 × 1080p at 50/60 Hz)
- WUXGA (1920 × 1200p at 60 Hz) reduced blanking format
- PC resolutions from VGA (640 × 480p at 60 Hz) to UXGA (1600 × 1200p at 60 Hz)
- Deep Color mode 10-bit and 12-bit (up to 205 MHz TMDS clock)
- IEC 60958/IEC 61937, One Bit Audio (SACD), DST (compressed DSD) and HBR stream
- Gamut boundary description

The TDA19978A includes:

- An improved audio clock generation (an external reference clock is used)
- An improved system for an accurate recognition of PC and TV formats
- The generation of a $128/256/512 \times f_s$ system clock allowing the use of simple audio DACs without integrated PLL, such as UDA1334BTS

Embedded oscillator (an external crystal can be used).

The TDA19978A converts a HDMI stream with or without HDCP into RGB or YCbCr digital signal.

The YCbCr digital output signal can be 4:4:4 or 4:2:2 semi-planar format following the ITU-R BT.601 standard or 4:2:2 ITU-R BT.656 format.

The TDA19978A can adjust the timing of the video port ($t_{su(o)}$ and $t_{h(o)}$).

All settings are controllable via the I²C-bus.



2. Features and benefits

- Compliant with HDMI 1.3a, DVI 1.0, CEA-861-D and HDCP 1.2 standards
- Quad independent HDMI inputs, up to 205 MHz (HDMI frequency)
- Embedded auto adaptive equalizer on HDMI links
- Embedded volatile EDID memory (253 shared bytes and three bytes dedicated per HDMI input) for zero, one, two, three or four HDMI inputs
- Support color depth processing (8-bit, 10-bit or 12-bit per color)
- Receive color Gamut Metadata Packet with interrupt on each update and readable on I²C-bus
- Up to four S/PDIF or I²S-bus outputs (eight channels) with a sampling rate up to 192 kHz with IEC 60958/IEC 61937 stream
- Support HBR audio stream up to 768 kHz with four demultiplexed S/PDIF or I²S-bus outputs
- Support HBR streams (e.g. DTS-HD master audio and Dolby TrueHD up to eight channels thanks to HBR packet for stream with a frame rate up to 768 kHz)
- Support DSD and DST audio stream up to six DSD channels output for SACD (support DST Audio Packet)
- Channel status decoder supporting multi-channels reception
- Improved audio clock generation using an external reference clock.
- Included system/master clock output ($128/256/512 \times f_s$) allowing to use the UDA1334BTS
- HDMI interface support all HDTV formats (up to 1920 × 1080p at 50/60 Hz) and up to UXGA (1600 × 1200p at 60 Hz) for PC's formats (WUXGA (1920 × 1200p at 60 Hz) reduced blanking supported)
- Embedded oscillator (an external crystal can be used)
- Frame and field detection for interlaced video signal
- Sync timing measurements for format recognition
- Improved system for measurements of blanking and video active area which allows an accurate recognition of PC and TV formats
- HDCP with repeater capability
- Embedded non-volatile memory to store HDCP keys
- Programmable color space conversion of RGB or YCbCr input signal into YCbCr or RGB
- Output format RGB 4:4:4, YCbCr 4:4:4, YCbCr 4:2:2 semi-planar following the ITU-R BT.601 standard or YCbCr 4:2:2 ITU-R BT.656
- 8-bit, 10-bit or 12-bit output formats (up to 10-bit only in 4:4:4 format) selectable via the I²C-bus
- Adjustable timing of video port ($t_{su(o)}$ and $t_{h(o)}$) via the I²C-bus
- Integrated downsampling-by-two with selectable filters on Cb and Cr channels for 4:2:2 mode
- Internal video and audio pattern generator
- Controllable via the I²C-bus; 5 V tolerant and bit rate up to 400 kbit/s
- DDC inputs 5 V tolerant and bit rate up to 400 kbit/s
- LV-TTL outputs
- Power-down mode

- CMOS process
- 1.8 V and 3.3 V power supplies
- Lead-free HLQFP144 package

3. Applications

- HDTV
- YCbCr or RGB high-speed video digitizer
- Projector, plasma and LCD TV
- Rear projection TV
- High-end TV
- Home theater amplifier
- DVD recorder
- AVR and HDMI splitter

4. Quick reference data

Table 1. Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
Digital inputs: pins RXxC+, RXxC- (x = A, B, C, D)						
$f_{\text{clk(max)}}$	maximum clock frequency		205	-	-	MHz
Clock timing output: pins VCLK, ACLK and SYSCLK						
$f_{\text{clk(max)}}$	maximum clock frequency	pin VCLK	165	-	-	MHz
		pin ACLK	25	-	-	MHz
		pin SYSCLK	50	-	-	MHz
Supplies						
$V_{\text{DDH(3V3)}}$	HDMI supply voltage (3.3 V)		3.135	3.3	3.465	V
$V_{\text{DDH(1V8)}}$	HDMI supply voltage (1.8 V)		1.71	1.8	1.89	V
$V_{\text{DDI(3V3)}}$	input supply voltage (3.3 V)		3.135	3.3	3.465	V
$V_{\text{DDC(1V8)}}$	core supply voltage (1.8 V)		1.71	1.8	1.89	V
$V_{\text{DDO(3V3)}}$	output supply voltage (3.3 V)		3.135	3.3	3.465	V
P	power dissipation	active mode	[1]			
		720p at 60 Hz	-	0.75	-	W
		1080p at 60 Hz	-	1.13	-	W
		1080p at 60 Hz; Deep Color mode	-	1.63	-	W
P_{cons}	power consumption	Power-down mode				
		pin PD = HIGH	-	1	-	mW
		I ² C-bus; EDID and HDCP memory power-up	-	4	-	mW
		I ² C-bus; EDID; activity detection and HDCP memory power-up	-	150	-	mW

[1] With 30 % of activity on video port output.

5. Ordering information

Table 2. Ordering information

Type number	Package		
	Name	Description	Version
TDA19978AHV	HLQFP144	plastic thermal enhanced low profile quad flat package; 144 leads; body 20 × 20 × 1.4 mm; exposed die pad	SOT612-3

6. Block diagram

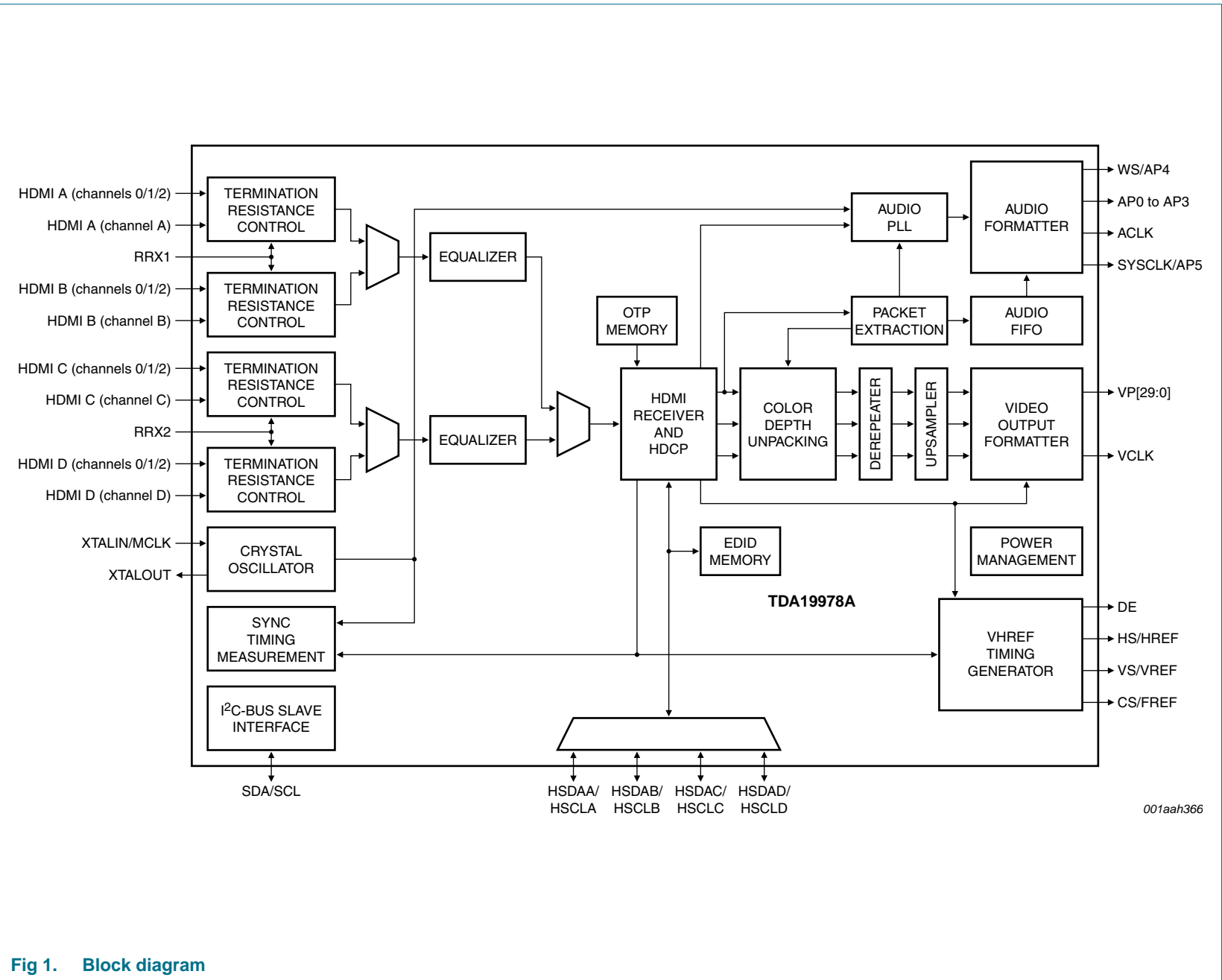


Fig 1. Block diagram

7. Limiting values

Table 3. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
$V_{DDx(3V3)}$	supply voltage on all 3.3 V pins		-0.5	+4.6	V
$V_{DDx(1V8)}$	supply voltage on all 1.8 V pins		-0.5	+2.5	V
ΔV_{DD}	supply voltage difference		-0.5	+0.5	V
I_O	output current		-	35	mA
T_{stg}	storage temperature		-55	+150	°C
T_{amb}	ambient temperature		0	70	°C
T_j	junction temperature		-	125	°C
V_{ESD}	electrostatic discharge voltage	HBM	-2000	+2000	V

8. Abbreviations

Table 4. Abbreviations

Acronym	Description
ACR	Audio Clock Regeneration
AVR	Audio Video Receiver
CMOS	Complementary Metal-Oxide-Semiconductor
DAC	Digital-to-Analog Converter
DDC-bus	Display Data Channel bus
DSD	Direct Stream Digital
DST	Direct Stream Transfer
DTS-HD	Digital Theater Systems HD
DVD	Digital Versatile Disc
DVI	Digital Video Interface
EDID	Extended Display Identification Data
HBM	Human Body Model
HBR	High-Bitrate
HD	High-Definition
HDCP	High-bandwidth Digital Content Protection
HDMI	High-Definition Multimedia Interface
HDTV	High-Definition TeleVision
LV-TTL	Low Voltage Transistor-Transistor Logic
OBA	One Bit Audio
OTP	One Time Programmable
PLL	Phase-Locked Loop
RGB	Red Green Blue
SACD	Super Audio CD
SVGA	Super Video Graphics Array
SXGA	Super eXtended Graphics Array

Table 4. Abbreviations ...continued

Acronym	Description
S/PDIF	Sony/Philips Digital Interface Format
TMDS	Transition Minimized Differential Signaling
UXGA	Ultra eXtended Graphics Array
VGA	Video Graphics Array
WUXGA	Wide Ultra eXtended Graphics Array
XGA	eXtended Graphics Array
YCbCr	Y = Luminance, Cb = Chroma blue, Cr = Chroma red
YUV	Y = Luminance, UV= Chroma

9. Revision history

Table 5. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
TDA19978A_SDS_3	20100511	Product data sheet	-	TDA19978A_SDS_1 ^[1]
Modifications:		<ul style="list-style-type: none"> • Section 1 “General description”: updated the Deep Color mode in 12-bit • Section 2 “Features and benefits”: replaced 225 MHz by 205 MHz • Table 1 “Quick reference data”: updated 		
TDA19978A_SDS_1	20080528	Objective data sheet	-	-

[1] Revision 2 is not available.

10. Legal information

10.1 Data sheet status

Document status ^{[1][2]}	Product status ^[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

[2] The term 'short data sheet' is explained in section "Definitions".

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